MT81P025N2

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P-Channel Enhancement Mode Field Effect Transistor

Product Summary

Features

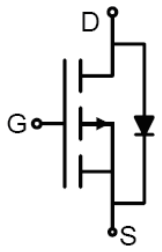
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

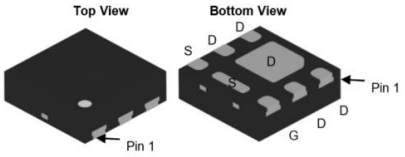
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	-15	V
$R_{DS(ON)\_TYP}$	26.3	mΩ
I_D	-7.0	A
Q_G	8.9	nC



Schematic Diagram



DFN2020-6L top&bottom view

Table 1. Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage (V_{GS}=0V)	-15	V
V_{GS}	Gate-Source Voltage (V_{DS}=0V)	±12	V
I_D	Drain Current-Continuous(T_A=25℃)	-7.0	A
	Drain Current-Continuous(T_A=100℃)	-4.5	A
$I_{DM\ (pluse)}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	-22.4	A
P_D	Maximum Power Dissipation(T_A=25℃)	1.6	W
	Maximum Power Dissipation(T_A=100℃)	0.6	W
E_{AS}	Avalanche energy (Note 2)	13	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		80	℃/W

Table 3. Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V I_D=-250μA	-15			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-15V, V_{GS}=0V T_J=25℃			-1	μA
		V_{DS}=-15V, V_{GS}=0V T_J=125℃			-100	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS}=±12V, V_{DS}=0V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250μA	-0.5		-1	V
g_{FS}	Forward Transconductance	V_{DS}=-5V, I_D=-2A		10		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	V_{GS}=-4.5V, I_D=-2A T_J=25℃		26.3	34.2	mΩ
$R_{DS(ON)}$	Drain-Source On-State Resistance	V_{GS}=-2.5V, I_D=-1.5A T_J=25℃		36.8	48.9	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}=-15V,V_{GS}=0V, f=1.0MHz		835		pF
C_{oss}	Output Capacitance			142		pF
C_{rss}	Reverse Transfer Capacitance			93		pF
Switching Parameters						
$t_{d(on)}$	Turn-on Delay Time	V_{GS}=-4.5V, V_{DS}=-15V, R_L=5Ω, R_{GEN}=3Ω		12		nS
t_r	Turn-on Rise Time			30		nS
$t_{d(off)}$	Turn-Off Delay Time			46		nS
t_f	Turn-Off Fall Time			52		nS
Q_g	Total Gate Charge	V_{GS}=-4.5V, V_{DS}=-15V, I_D=-3A		8.9		nC
Q_{gs}	Gate-Source Charge			1.5		nC
Q_{gd}	Gate-Drain Charge			2.1		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-7.0	A
V_{SD}	Forward on Voltage (Note 3)	V_{GS}=0V, I_S=-3A			-1.2	V

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.
Notes 2.E_{AS} condition: T_J=25℃,V_{DD}=-20V,V_G=-10V, Rg=25Ω, L=0.5mH.
Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

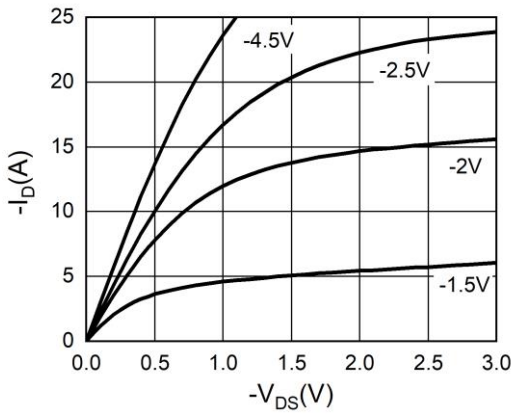


Figure 2. Transfer Characteristics

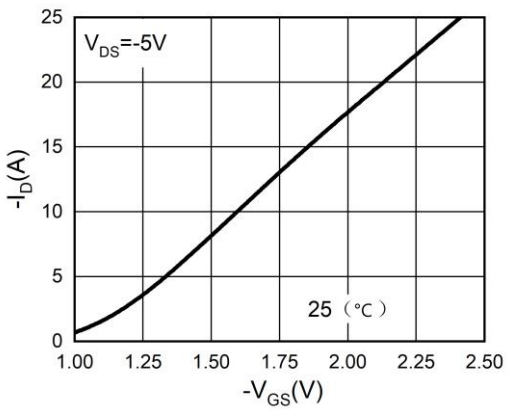


Figure 3. Power Dissipation

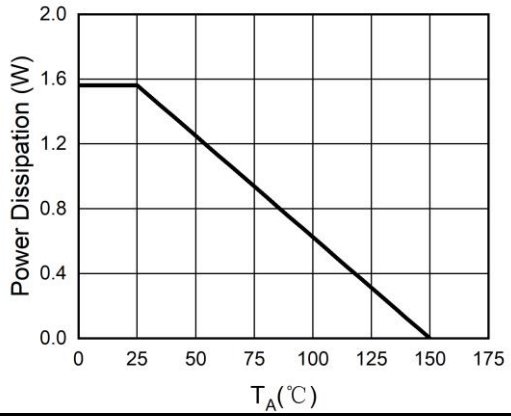


Figure 4. Drain Current

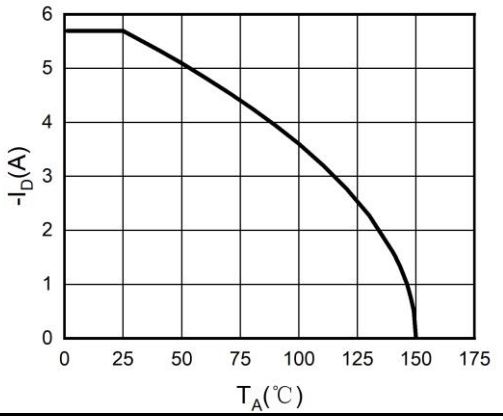


Figure 5. BV_{DSS} vs Junction Temperature

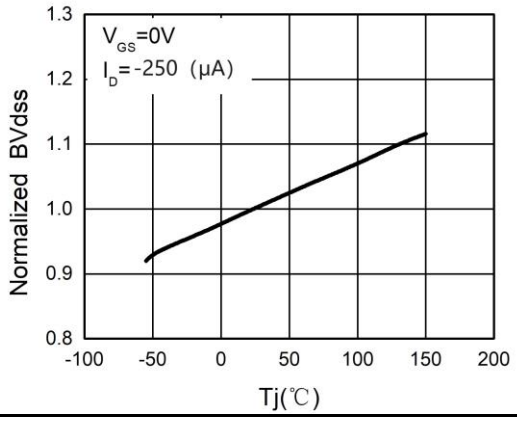
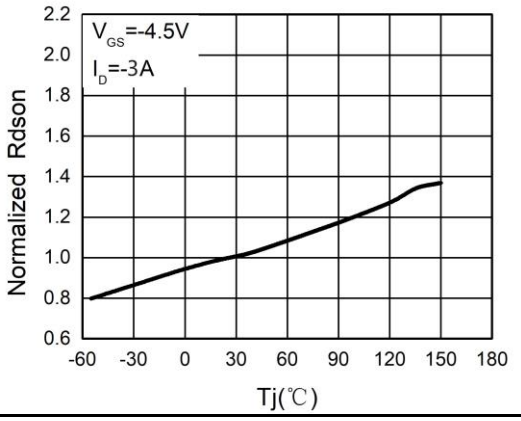


Figure 6. $R_{DS(ON)}$ vs Junction Temperature



Typical Electrical And Thermal Characteristics (Curves)

Figure 7. Gate Charge Waveforms

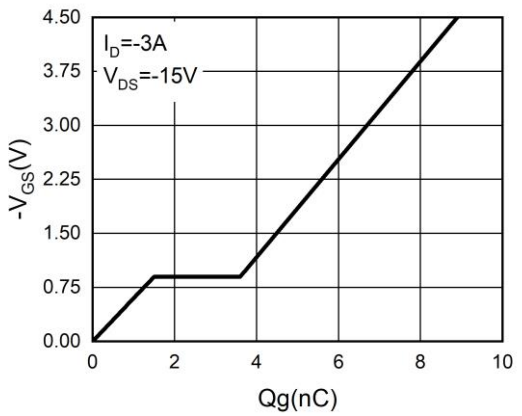


Figure 8. Capacitance

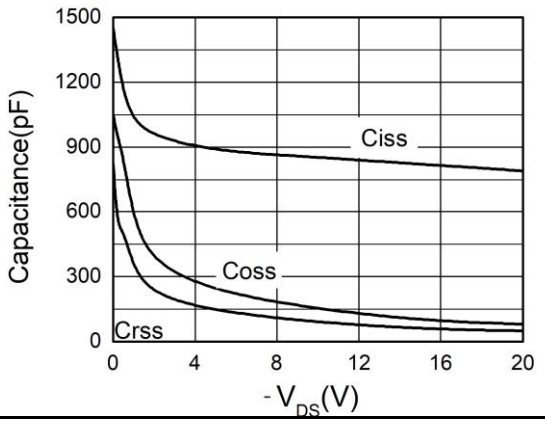


Figure 9. Body-Diode Characteristics

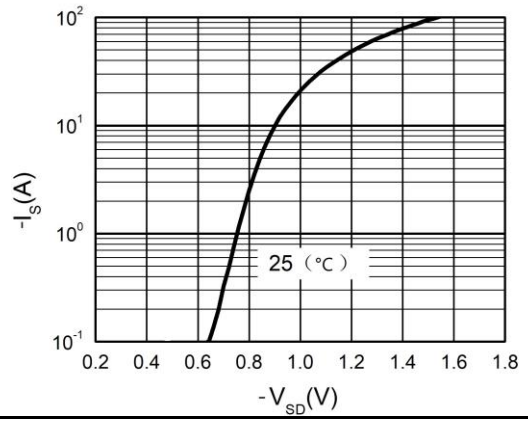
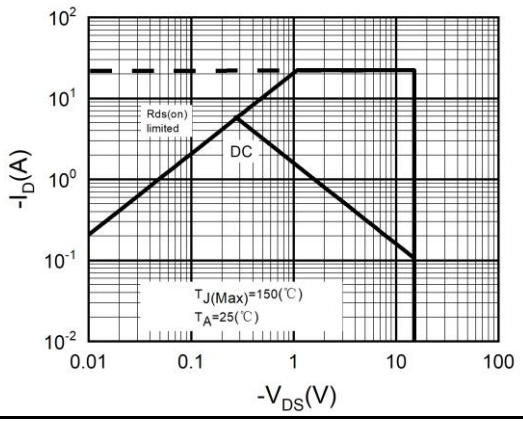
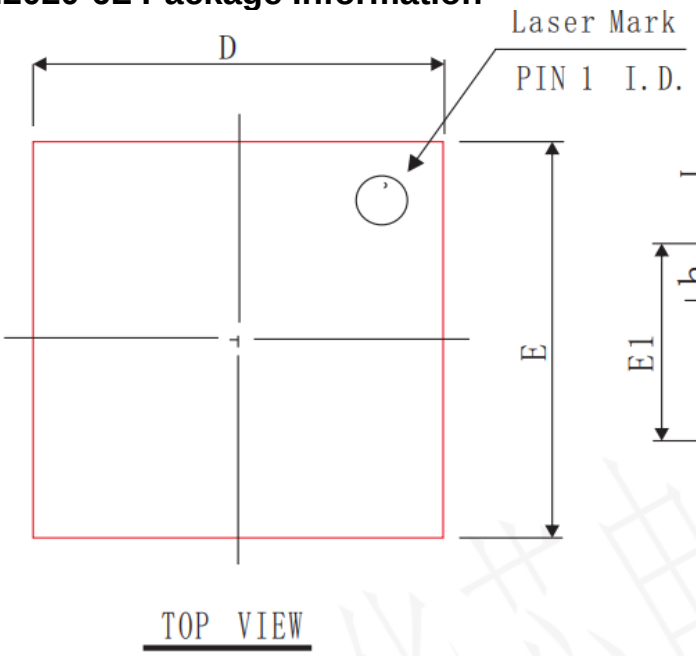


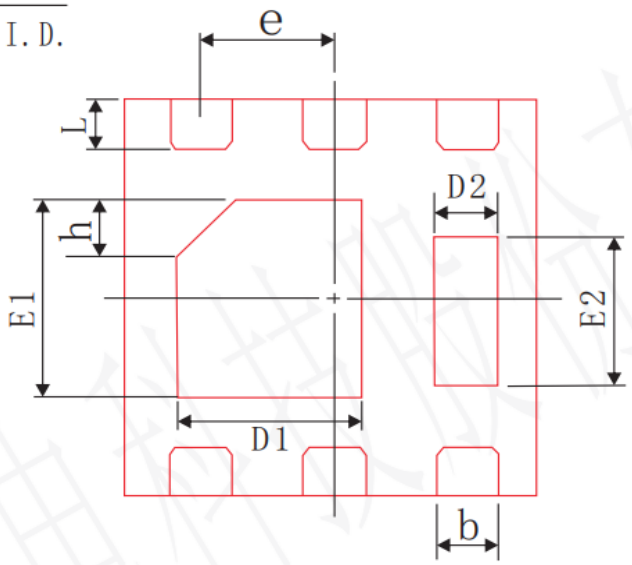
Figure 10. Maximum Safe Operating Area



DFN2020-6L Package Information



TOP VIEW



BOTTOM VIEW

SYMBOL	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.20	0.25	0.30
D	1.95	2.00	2.07
E	1.95	2.00	2.07
D1	0.80	0.90	1.00
E1	0.90	1.00	1.10
D2	0.20	0.30	0.40
E2	0.65	0.75	0.85
L	0.20	0.25	0.35
h	0.20	0.25	0.30
c	0.203 REF		
e	0.65 BSC		

SIDE VIEW

其它厚度尺寸如下

A	0.55	0.60	0.65
A	0.50	0.55	0.60

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